

NOT RECOMMENDED FOR NEW DESIGN USE DMN2053UW



DMN2065UW

20V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C
20V	$56m\Omega$ @ V _{GS} = $4.5V$	2.8A
	$65m\Omega$ @ $V_{GS} = 2.5V$	2.6A
	$93m\Omega @ V_{GS} = 1.8V$	2.2A
	140mΩ @ V _{GS} = 1.5V	1.8A

Description and Applications

This MOSFET has been designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- General Purpose Interfacing Switch
- Power Management Functions
- DC-DC Converters
- Analog Switch

Features and Benefits

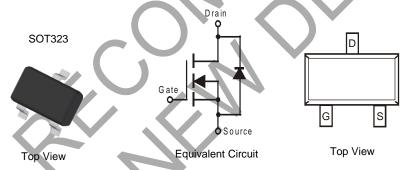
- Low On-Resistance
- Low Input Capacitance
 - Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at

https://www.diodes.com/products/automotive/automotive-products/.

- This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability. https://www.diodes.com/quality/product-definitions/
- An Automotive-Compliant Part is Available Under Separate Datasheet (DMN2065UWQ)

Mechanical Data

- Case: SOT323
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Alloy42 Leadframe.
 Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.027 grams (Approximate)



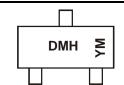
Ordering Information (Note 4)

Part Number	Case	Packaging
DMN2065UW-7	SOT323	3000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

- See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



DMH = Product Type Marking Code YM = Date Code Marking

Y = Year (ex: I = 2021)

M = Month (ex: 9 = September)

Date Code Key

Year	2011		2021	2022	2023	2024	2025	2026	2027	2028	2029	2030
Code	Υ			J	K	L	М	N	0	Р	R	S
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	VDSS	20	V		
Gate-Source Voltage	V_{GSS}	±12	V		
Continuous Drain Current (Note 6) \/ 45\/	Steady State	$T_A = +25$ °C $T_A = +70$ °C	lD	2.8 2.3	А
Continuous Drain Current (Note 6) V _{GS} = 4.5V	t<10s	$T_A = +25$ °C $T_A = +70$ °C	ID	3.1 2.6	Α
Continuous Drain Current (Note 6) Vac. 4 9)	Steady State	$T_A = +25$ °C $T_A = +70$ °C	lo	2.2 1.7	А
Continuous Drain Current (Note 6) V _{GS} = 1.8V	t<10s	$T_A = +25$ °C $T_A = +70$ °C	I _D	2.4 1.9	А
Pulsed Drain Current (10us Pulse, Duty Cycle=1%)	IDM	30	Α		
Maximum Body Diode Forward Current (Note 5)			Is	1.2	Α

Thermal Characteristics (@ $T_A = +25$ °C, unless otherwise specified.)

Symbol	Value	Unit
PD	0.43	W
D	296	°C/W
R _θ JA	252	°C/W
PD	0.7	W
	178	°C/W
ReJA	151	°C/W
TJ, TSTG	-55 to +150	°C
	ReJA	R _{θJA} 296 252 P _D 0.7 R _{θJA} 178 151

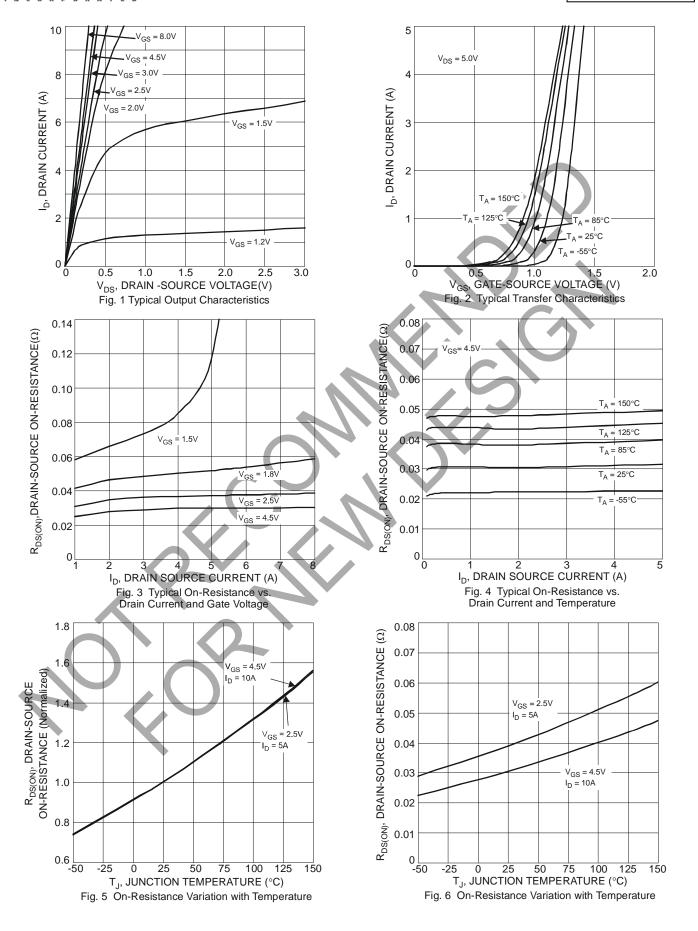
Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

		4				
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BVpss	20			V	$V_{GS} = 0V$, $I_D = 1mA$
Zero Gate Voltage Drain Current @T _C = +25°C	Ipss		_	1	μA	$V_{DS} = 20V$, $V_{GS} = 0V$
Gate-Source Leakage	Igss	1	_	±1	μΑ	$V_{GS} = \pm 10V$, $V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	Vgs(TH)	0.35	_	1.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$
		_	52	56		$V_{GS} = 4.5V, I_{D} = 2A$
Static Drain-Source On-Resistance	Program	_	59	65	mΩ	$V_{GS} = 2.5V, I_D = 2A$
Static Dialif-Source Off-Resistance	RDS(ON)	_	60	93	11152	$V_{GS} = 1.8V, I_{D} = 1A$
	•	_	75	140		$V_{GS} = 1.5V, I_D = 0.5A$
Forward Transfer Admittance	Y _{fs}	_	7		S	$V_{DS} = 5V, I_D = 3.8A$
Diode Forward Voltage	VsD	_	0.7	1.0	V	$V_{GS} = 0V$, $I_{S} = 1A$
DYNAMIC CHARACTERISTICS (Note 8)						•
Input Capacitance	Ciss	_	400.0		pF	101/11/
Output Capacitance	Coss	_	73.8	_	pF	$V_{DS} = 10V, V_{GS} = 0V,$ - f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	65.6		pF	1 = 1.000112
Total Gate Charge	Qg	_	5.4		nC	$V_{GS} = 4.5V, V_{DS} = 10V,$
Gate-Source Charge	Qgs	_	0.7		nC	I _D = 6A
Gate-Drain Charge	Qgd	_	1.4		nC	
Turn-On Delay Time	t _{D(ON)}	_	3.5		ns	
Turn-On Rise Time	t _R	_	9.7		ns	V _{DD} = 10V, V _G s = 5V,
Turn-Off Delay Time	tD(OFF)	_	23.8		ns	$R_L = 1.7\Omega$, $R_G = 6\Omega$
Turn-Off Fall Time	t _F	_	7.2	_	ns	

Notes:

- 5. Device mounted on FR-4 substrate PC board, with minimum recommended pad layout.6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to product testing.







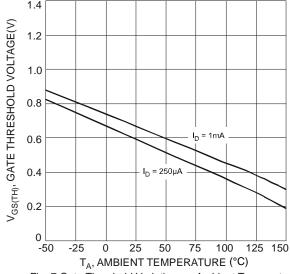
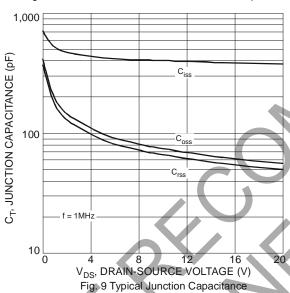
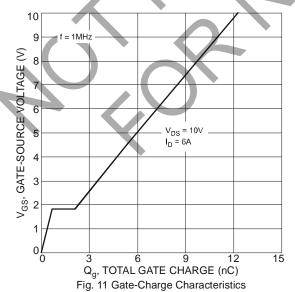
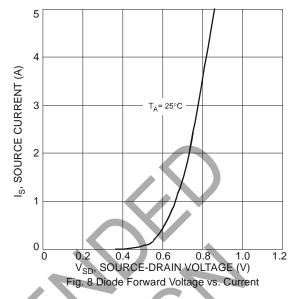


Fig. 7 Gate Threshold Variation vs. Ambient Temperature







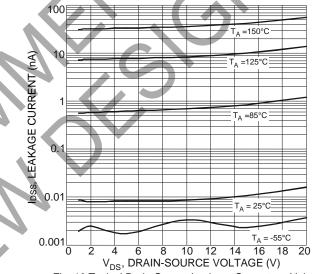
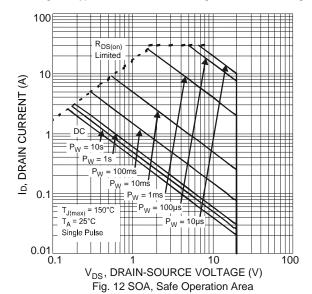
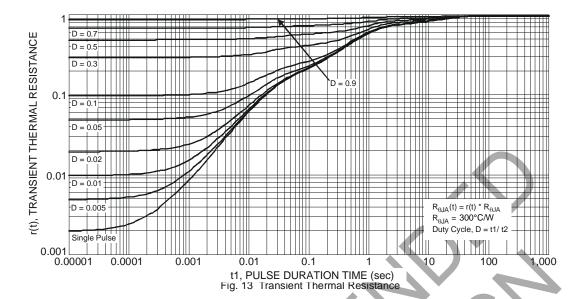


Fig. 10 Typical Drain-Source Leakage Current vs. Voltage





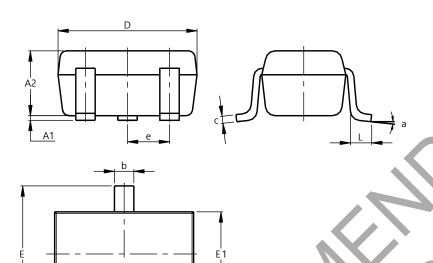




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

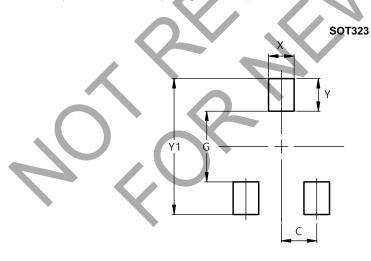
SOT323



	SOT323						
Dim	Min	Max	Тур				
A1	0.00	0.10	0.05				
A2	0.90	1.00	0.95				
b	0.25	0.40	0.30				
C	0.10	0.18	0.11				
D	1.80	2.20	2.15				
E	2.00	2.20	2.10				
E1 `	1.15	1.35	1.30				
е	9).650 B	SC				
e1	1.20	1.40	1.30				
F	0.375	0.475	0.425				
L	0.25	0.40	0.30				
a	0°	8°					
All	Dimen	sions	in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	0.650
G	1.300
Х	0.470
Y	0.600
Y1	2.500



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